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Schmid(10) **Pub. No.: US 2022/0361341 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **METHOD OF PRODUCING PRINTED
CIRCUIT BOARDS AND PRINTED CIRCUIT
BOARDS PRODUCED IN ACCORDANCE
WITH THE METHOD***H05K 1/11* (2006.01)*H05K 3/00* (2006.01)(52) **U.S. Cl.**CPC *H05K 3/107* (2013.01); *H05K 1/0298*
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ABSTRACT

A method of producing a multilayer printed circuit board includes a metallic conductor structure including providing a base substrate including a film or plate and having first and second substrate sides, which base substrate at least partly consists of an electrically non-conductive organic polymer material and wherein the first substrate side is covered with a cover metal layer, partially removing the cover metal layer while subdividing the first substrate side into at least one first partial area, in which the first substrate side is free of the cover metal layer, and into at least one second partial area, in which the first substrate side is covered with the cover metal layer, and causing a plasma to act on the first substrate side with the aid of which plasma the polymer material is removed in the at least one first partial area while forming at least one trench.

